WHAT IS CLAIMED IS:

1. A plurality of chip devices comprising:

a plurality of bottom leadframes each including a plurality of leads;

a plurality of bumped dies, each bumped die being on a corresponding bottom leadframe and including a source and gate solder bump array;

a plurality of top leadframes, each top leadframe being coupled to a corresponding bumped die and including a plurality of leads; and

four rails, a first rail being connected to a first side of each of the top leadframes, a second rail being connected to a second side of each of the top leadframes, a third rail being connected to a first side of each of the bottom leadframes, and a fourth rail being connected to a second side of each of the bottom leadframes;

wherein each bottom leadframe has leads coupled to drain terminals on its corresponding bumped die;

wherein each top leadframe has a lead coupled to a gate terminal on its corresponding bumped die and leads coupled to source terminals on its corresponding die; and

wherein the first rail is coupled to the third rail and the second rail is coupled to the fourth rail.

2. An arrangement in accordance with claim 1 wherein the solder bumps consist of one of Pb-Sn, Pb-Sn-Ag or Sn-Sb.

3. An arrangement in accordance with claim 1 wherein the leads are coupled to the gate terminal and the source terminals via pads.

4. An arrangement in accordance with claim 1 further comprising a plurality of molded bodies, each body encapsulating a portion of a corresponding top leadframe and a corresponding bottom leadframe, and a corresponding bumped die therebetween.

5. An arrangement in accordance with claim 1 wherein the chip devices are DMOS devices.

6. An arrangement in accordance with claim 1 wherein the top leadframes include slots defined therein.

7. A method of making a chip device, the method comprising:

providing a plurality of bottom leadframes coupled to one another with a pair of rails;

attaching a corresponding bumped die including a source and gate solder bump array to each bottom leadframe;

providing a plurality of top leadframes coupled to one another with a pair of rails; and

flipping the plurality of top leadframes such that each top leadframe contacts the solder bumps on a corresponding bumped die,.

8. A method in accordance with claim 7 further comprising placing a molded body around each top and bottom leadframe with a corresponding bumped die therebetween.

9. A method in accordance with claim 7 further comprising spot welding a rail of the bottom leadframe and a rail of the top leadframe together.

10. A method in accordance with claim 9 further comprising reflowing the solder bumps.

11. A method in accordance with claim 7 further comprising pressfitting a rail of the bottom leadframe and a rail of the top leadframe together.

12. A method in accordance with claim 11 further comprising reflowing the solder bumps.

13. A method in accordance with claim 7 wherein the bumped die is attached to the bottom leadframe with an adhesive, the adhesive being cured sometime during the method after the die is attached thereto.

14. A method in accordance with claim 7 wherein the bumped die is attached to the bottom leadframe with soft solder.

15. A method of making a plurality of chip devices, the method comprising:

providing a plurality of top leadframes coupled to one another with a pair of rails;

flipping a bumped die including a source and gate solder bump array on each top leadframe such that each bumped die contacts the gate and source pads of topframe; and

providing a plurality of bottom leadframes being coupled to one another with a pair of rails;

flipping the top leadframes onto the plurality of bottom leadframes such that a bumped die is between each top leadframe and a corresponding bottom leadframe.

16. A method in accordance with claim 15 further comprising placing a molded body around each top and bottom leadframe with a corresponding bumped die therebetween.

17. A method in accordance with claim 15 further comprising spot welding a rail of the bottom leadframe and a rail of the top leadframe together.

18. A method in accordance with claim 17 further comprising reflowing the solder bumps.

19. A method in accordance with claim 15 further comprising pressfitting a rail of the bottom leadframe and a rail of the top leadframe together.

20. A method in accordance with claim 19 further comprising reflowing the solder bumps.

21. A method in accordance with claim 15 wherein the die is attached to the bottom leadframe with soft solder.

22. A method in accordance with claim 15 wherein the die is attached to the bottom leadframe with an adhesive, the adhesive being cured sometime during the method after the die is attached thereto.

23. A method of making a plurality of chip devices, the method comprising:

providing a plurality of top leadframes coupled to one another with a pair of rails;

providing a plurality of bottom leadframes coupled to one another with a pair of rails, each bottom leadframe including a die attach pad;

placing a bumped die including a source and gate array on each die attach pad of each bottom leadframe; and

coupling the top and bottom leadframe rails together such that each bumped die contacts the solder bumps of a corresponding top leadframe.

24. A method in accordance with claim 23 further comprising placing a molded body around each top and bottom leadframe with a corresponding bumped die therebetween.

25. A method in accordance with claim 23 further comprising spot welding the rails of the bottom leadframe and the rails of the top leadframe together.

26. A method in accordance with claim 25 further comprising reflowing the solder bumps.

27. A method in accordance with claim 23 further comprising pressfitting the rails of the bottom leadframe and the rails of the top leadframe together.

28. A method in accordance with claim 27 further comprising reflowing the solder bumps.

29. A method in accordance with claim 23 wherein each bumped die is attached to the bottom leadframe with an adhesive, the adhesive being cured sometime during the method after the die is attached thereto.

30. A method in accordance with claim 23 wherein each bumped die is attached to the bottom leadframe with soft solder.

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